

RTL8762AK-CG



(CONFIDENTIAL: Development Partners Only)

Rev. 1.0

29 June 2015

Track ID: JATR-8275-15



Realtek Semiconductor Corp.

No. 2, Innovation Road II, Hsinchu Science Park, Hsinchu 300, Taiwan Tel.: +886-3-578-0211. Fax: +886-3-577-6047

www.realtek.com



COPYRIGHT

© 2015 Realtek Semiconductor Corp. All rights reserved. No part of this document may be reproduced, transmitted, transcribed, stored in a retrieval system, or translated into any language in any form or by any means without the written permission of Realtek Semiconductor Corp.

DISCLAIMER

Realtek provides this document 'as is', without warranty of any kind. Realtek may make improvements and/or changes in this document or in the product described in this document at any time. This document could include technical inaccuracies or typographical errors.

TRADEMARKS

Realtek is a trademark of Realtek Semiconductor Corporation. Other names mentioned in this document are trademarks/registered trademarks of their respective owners.

USING THIS DOCUMENT

This document is intended for the software engineer's reference and provides detailed programming information.

Though every effort has been made to ensure that this document is current and accurate, more information may have become available subsequent to the production of this guide.

REVISION HISTORY

Revision	Release Date	Summary
1.0	2015/07/7	First release.



Table of Contents

1.	G	GENERAL DESCRIPTION	1
2.	FI	EATURES	1
۷.	. Li	EATURES	•••••
3.	B]	SLOCK DIAGRAM	4
			_
4.	P	PIN ASSIGNMENTS	5
	4.1.	PACKAGE IDENTIFICATION	5
5.	. P]	IN DESCRIPTIONS	6
	5.1.	Power-On Trap Pins	<i>€</i>
	5.2.		
	5.3.		
	5.4.		
	5.5.		
	5.6.	GROUND PINS	7
	5.7.	GPIO PINS	7
6.	E]	LECTRICAL AND THERMAL CHARACTERISTICS	8
	6.1.		5
	6.2.	POWER SUPPLY DC CHARACTERISTICS	۶۶
	6.3.	DIGITAL IO PIN DC CHARACTERISTICS	c
	6.4.	Power Consumption	10
		.4.1. GPS Mode Power Consumption	10
	6.4	.4.2. GPS/Beidou Mode Power Consumption	10
		.4.3. GPS/Glonass Mode Power Consumption	10
	6.5.	UART Interface Characteristics	10
	6.6.	UART Interface	10
	6.	.6.1. UART Interface Signal Levels	10
	6.	DIGITAL IO PIN DC CHARACTERISTICS POWER CONSUMPTION	10
7.	M	AECHANICAL DIMENSIONS	11
	7.1.	MECHANICAL DIMENSIONS NOTES	12
8.	0	ORDERING INFORMATION	12



List of Tables

TABLE 1. POWER-ON TRAP PINS	
Table 2. RF Interface	7
TABLE 3. ENABLE AND WAKEUP	
TABLE 4. CLOCK AND OTHER PINS	7
TABLE 5. POWER PINS	7
TABLE 6. GROUND PINS	7
TABLE 7. GPIO PINS	7
TABLE 8. TEMPERATURE LIMIT RATINGS	8
TABLE 9. POWER SUPPLY DC CHARACTERISTICS	8
TABLE 10. DIGITAL IO PIN DC CHARACTERISTICS	
TABLE 11. GPS MODE POWER CONSUMPTION.	10
TABLE 12. GPS/BEIDOU MODE POWER CONSUMPTION	10
TABLE 13. GPS/GLONASS MODE POWER CONSUMPTION	10
TABLE 14. UART INTERFACE POWER-ON TIMING PARAMETERS	10
TABLE 15. UART INTERFACE POWER-ON SEQUENCE	10
TABLE 16. UART INTERFACE POWER ON TIMING PARAMETERS	10
TABLE 17. ORDERING INFORMATION.	12

List of Figures

FIGURE 1.	BLOCK DIAGRAM	11				4
FIGURE 2.	PIN ASSIGNMENTS	7			<u> </u>	5
FIGURE 3.	UART INTERFACE WAVEFORM		7.7			U
FIGURE 4.	UART Power-On Sequence without Harry ar	E F		v Coi	NTROL1	C
FIGURE 5.	UART POWER ON SEQUENCE WITH HARDWARE YN	OW	Č	NTRO	DL1	(
1100122.	OTHER TO WELL ON DESCRIPTION WITH THE	S	•		,	`



1. General Description

The RTL8762AK is an ultra-low power system on chip solution for Bluetooth low energy applications. The RTL8762AK combines the excellent performance of a leading RF transceiver with ARM Cortex M0, 256KB eflash, 80KB RAM, and rich powerful supporting features and peripherals. The RTL8762AK integrates a sigma-delta ADC, programmable gain amplifier and microphone bias circuit for voice command application. The RTL8762AK embeds IR transceiver, hardware keyscan, and Quad-decoder on a single IC. The RTL8762AK comes with QFN56 package.





2. Features

General

- Ultra low power consumption with intelligent PMU
- Support the Bluetooth 4.2 core specification
- Integrate MCU to execute Bluetooth protocol stack
- Support fully multiple Low Energy states
- Support LE L2CAP Connection Oriented Channel Support
- Support LE low duty directed advertising
- Support LE data length extension feature
- Support OTA (Over-the-Air) programming mechanism for firmware upgrade
- Support internal 32KHz OSC or external 32KHz clock input for low power mode
- Support GAP, ATT/GATT, SMP, L2CA
- Generic Applications for GAP Central, Peripheral, Observer and Broadcaster Roll

Platform

- ARM Cortex-M0 (Maximum 52MHz)
- 256KB embedded flash
- 80KB RAM
- 2KB e-fuse
- Support AES128/192/256 encrypt/decrypt engine

Bluetooth Transceiver

- Fast AGC control to improve receiving dynamic range
- Support Bluetooth Low Energy PHY

Peripheral Interfaces

- Flexible General Purpose IOs (31GPIOs with 56QFN)
- Three configurable LED pins
- Hardware Keyscan
- Quad-decoder x3
- Embed IR transceiver
- Real-time counters (RTC)
- Support 3wire/2wire SPI
- Support Low power comparator
- Timer x 8
- I2C x 2
- PWM x 4
- Support 40MHz XTAL
- Support audio ADC for voice command application

Application

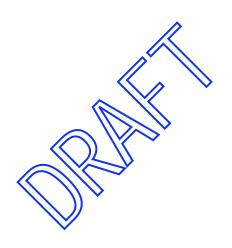
- Keyboard
- Mouse



- TV Remote Controller
- LE HID

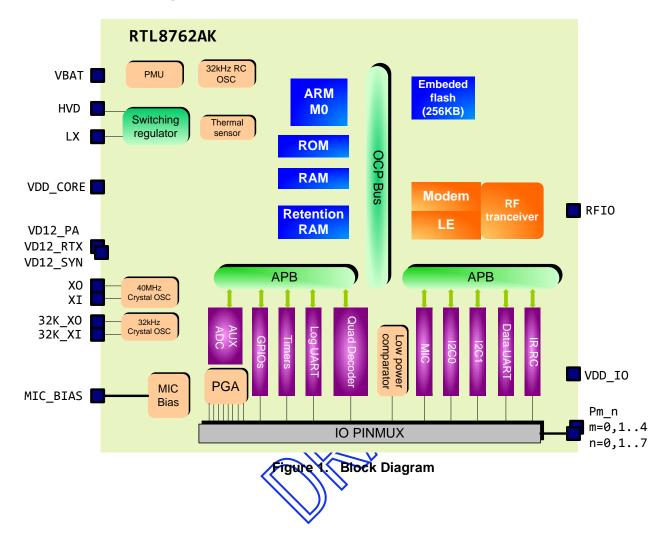
Package

■ 56-pin 7mmx7mm QFN



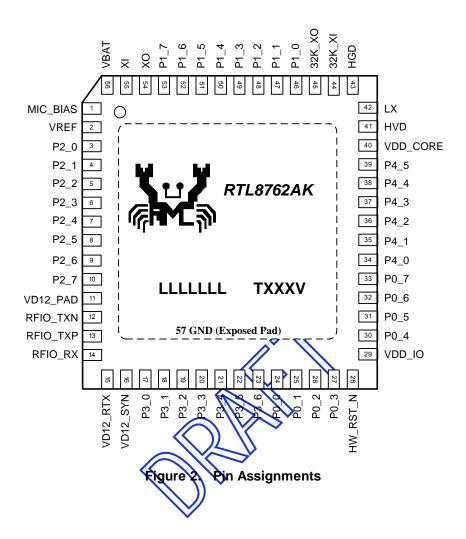


3. Block Diagram





4. Pin Assignments



4.1. Package Identification

Green package is indicated by the 'G' in GXXXXV (Figure 2).



5. Pin Descriptions

The following signal type codes are used in the tables:

I: Input

O: Output

P: Power

5.1. RF Interface

Table 1. RF Interface

Symbol	Type	Pin No	Description
RFIO_RX I 14		14	BT RX signal / BT TX signal(low power mode)
RFIO_TXN O 12		12	BT TX signal (for high power mode)
RFIO_TXP	О	13	BT TX signal (for high power mode)

5.2. XTAL and System Interface

Table 2. XTAL Interface

Symbol	Type	Pin No	Description
32K_XI	I	44	32k crystal input or external 32k clock input
32K_XO	0	45	32k crystal output
XI	I	55	40MHz crystal input or external 40MHz clock input
XO	O	54	40MN2 crystal output
HW_RST_N	I	28	Hardware reset pin, low active

5.3. General Purpose IOs

Table 3. General Purpose IOs

14010 01 001101411 41 1000 100							
Symbol	Type	Pin No	Description				
P0_0	Ю	24	General purpose IO				
P0_1	IO	25	General purpose IO				
P0_2	IO	26	General purpose IO, 20mA driving capability				
P0_3	IO	27	General purpose IO, 20mA driving capability				
P0_4	IO	30	General purpose IO, 20mA driving capability				
P0_5	IO	31	General purpose IO, 20mA driving capability				
P0_6	Ю	32	General purpose IO				
P0_7	IO	33	General purpose IO				
P1_0	Ю	46	General purpose IO, SWDIO(default)				
P1_1	IO	47	General purpose IO, SWDCLK(default)				
P1_2	IO	48	General purpose IO				
P1_3	Ю	49	General purpose IO				



Symbol	Type	Pin No	Description		
P1_4	IO	50	General purpose IO		
P1_5	IO	51	General purpose IO		
P1_6	Ю	52	General purpose IO		
P1_7	IO	53	General purpose IO		
P2_0	Ю	3	General purpose IO		
P2_1	IO	4	General purpose IO		
P2_2	Ю	5	General purpose IO		
P2_3	Ю	6	General purpose IO		
P2_4	IO	7	General purpose IO		
P2_5	IO	8	General purpose IO		
P2_6	Ю	9	General purpose IO		
P2_7	IO	10	General purpose IO		
P3_0	Ю	17	General purpose IO		
P3_1	IO	18	General purpose IO, UART_RX(default)		
P3_2	IO	19	General purpose IO		
P3_3	IO	20	General purpose IO		
P3_4	IO	21	General purpose IO		
P3_5	Ю	22	General purpose IO		
P3_6	IO	23	General purpose IO		
P4_0	Ю	34	General purpose IO, SPIO_CLK(default)		
P4_1	IO	35	General purpose IO, SPIG MISO(default)		
P4_2	IO	36	General purpose IO_SPIO_MOSI(default)		
P4_3	IO	37	General purpose N, SPIO_CS N(default)		
P4_4	IO	38	General purpose 10		

5.4. Power Pins

Table 4. Power Pins

Symbol	Type	Pin No	Description	
VREF	P	2	ADC reference voltage (decouple)	
VD12_PAD	P	11	supply 1.2V power for PA	
VD12_RTX	P	15	supply 1.2V power for RF transceiver	
VD12_SYN	P	16	supply 1.2V power for synthesizer	
VDD_IO	P	29	supply 1.8V~3.3V power for digital IO PADs	
VDD_CORE	P	40	supply 1.2V power for digital core	
HVD	P	41	supply 2.6~3.3V power for Switching regulator input	
LX	P	42	Switching regulator output	
HGD	P	43	Ground for switching regulator	
VBAT	P	56	Battery voltage input	
MIC_BIAS	P	1	Microphone bias	



6. Electrical and Thermal Characteristics

6.1. Temperature Limit Ratings

Table 5. Temperature Limit Ratings

Parameter	Minimum	Maximum	Units
Storage Temperature	-55	+125	°C
Ambient Operating Temperature	0	+70	°C
Junction Temperature	0	+125	°C

6.2. Power Supply DC Characteristics

Table 6. Power Supply DC Characteristics

· and or · · or									
Parameter	Minimum	Typical	Maximum	Units					
Single power source of whole chip	1.8	3	3.6	V					
		1							
1.2V Core and RFAFE Supply	1.10	1.2	1.22	3.7					
Voltage	1.10	1.2	1.32	V					
Power for digital IO PADs	84	-	3.6	V					
Power for switching regulator	1.8	-	3.6	V					
	Parameter Single power source of whole chip 1.2V Core and RFAFE Supply Voltage Power for digital IO PADs	Parameter Minimum Single power source of whole chip 1.8 1.2V Core and RFAFE Supply Voltage 1.10 Power for digital IO PADs	Parameter Minimum Typical Single power source of whole chip 1.8 3 1.2V Core and RFAFE Supply Voltage 1.10 1.2 Power for digital IO PADs - -	Parameter Minimum Typical Maximum Single power source of whole chip 1.8 3 3.6 1.2V Core and RFAFE Supply Voltage 1.10 1.2 1.32 Power for digital IO PADs - 3.6					

Note: VDD_IO\(\leq\)VBAT

6.3. Digital IO Pin DC Characteristics

Table 7. 3.3V IO Pin DC Characteristics

Symbol	Parameter	Minimum	Normal	Maximum	Units
V_{IH}	Input high voltage	2.0	3.3	3.6	V
$V_{\rm IL}$	Input low voltage	-	0	0.9	V
V_{OH}	Output high voltage	2.97	-	3.3	V
V _{OL}	Output low voltage	0	-	0.33	V



Table 8. 2.8V IO Pin DC Characteristics

Symbol	Parameter	Minimum	Normal	Maximum	Units
V_{IH}	Input high voltage	1.8	2.8	3.1	V
$V_{\rm IL}$	Input low voltage	-	0	0.8	V
V _{OH}	Output high voltage	2.5	-	3.1	V
V _{OL}	Output low voltage	0	-	0.28	V





6.4. Power Consumption

6.4.1. Low Power Mode

Table 9. Low Power Mode

Power mode	Always on registers	32k RCOSC/XTAL	Retention SRAM	CPU	Wakeup method	Current consumption (VBAT=3V)
Power down	ON	OFF	OFF	OFF	Wakeup by GPIO	TBD
Hibernate	ON	ON	OFF	OFF	Wakeup by GPIO or RTC	TBD
Deep LPS	ON	ON	Retention	OFF	Wakeup by GPIO, timer	TBD

6.4.2. Active Mode

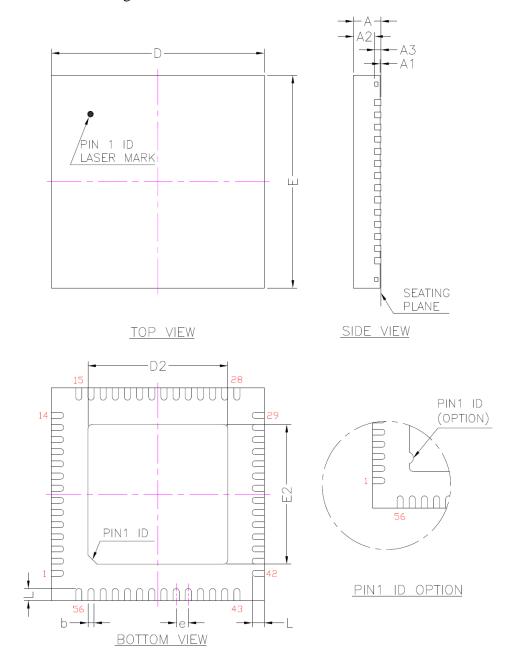
Table 10. Active Mode

1 4 5 1 5 1 7 1 5 1 1 5 1 1 5 1 1					
Power Mode	Current Consumption				
	(VBAT=3V)				
Active RX mode	₹ ₹ ₹ ₹ ₹ ₹ ₹ ₹ ₹ ₹ ₹ ₹ ₹ ₹ ₹ ₹ ₹ ₹ ₹				
Active TX mode	T BD				



7. Mechanical Dimensions

Plastic Quad Flat No Lead Package 56 Leads 7x7mm² Outline





7.1. Mechanical Dimensions Notes

Symbol	Dimension in mm			Dimension in inch		
Symbol	Min	Nom	Max	Min	Nom	Max
Α	0.80	0.85	0.90	0.031	0.033	0.035
A_1	0.00	0.02	0.05 0.000 0.001 0.00		0.002	
A_2		0.65	0.70		0.026	0.028
A_3	0.2 REF			0.008 REF		
b	0.15	0.20	0.25	0.006 0.008 0.0		0.010
D/E	7.00 BSC 0.276 BSC					
D ₂ /E ₂	4.35	4.60	4.85	0.171	0.181	0.191
е	0.40 BSC		0.016 BSC			
L	0.30	0.40	0.50	50 0.012 0.016 0.020		0.020

Notes:

- 1. CONTROLLING DIMENSION: MILLIMETER(mm).
- 2. REFERENCE DOCUMENTL: JEDEC MO-220.

8. Ordering Information

Table 11. Ordering Information

Part Number	Package	Status
RTL8762AK-CG	QFN-56, 'Green' Package	MP

Note: See page 5 for package identification.

Realtek Semiconductor Corp.

Headquarters

No. 2, Innovation Road II, Hsinchu Science Park,

Hsinchu 300, Taiwan, R.O.C.

Tel: 886-3-5780211 Fax: 886-3-5776047

www.realtek.com